Materials Declaration

Package	BGA
Body Size	27 X 27
Ball Count	297
Option	Pb-Free
Ball Size	0.6mm

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	10	1.22E-01	47627
SiO2 Filler	77	9.40E-01	366728
Phenol Resin	10	1.22E-01	47627
Carbon Black	0.5	6.11E-03	2381
Metal Hydroxide	2.5	3.05E-02	11907

Laminate

Item	% of Laminate	Weight (g)	PPM
BT-Epoxy	25	2.71E-01	105691
Glass Fiber	25	2.71E-01	105691
Copper	19	2.06E-01	80325
Nickel	11	1.19E-01	46504
Gold	7.8	8.46E-02	32975
Solder Mask (AUS303)	12.2	9.97E-02	38894

Solder Ball

	% of Solder Ball	Weight (g)	PPM
Sn	96.5	2.40 E-01	93600
Ag	3	7.46 E-03	2909
Cu	0.5	1.24 E-03	484

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99	6.01 E-03	2344

Chip

	% of Chip	Weight (g)	PPM
Si	100	3.19 E-02	12441

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	75	3.60 E-03	1404
Resin	5	2.40 E-04	94
Diester	12.5	6.00 E-04	234
Functionalized urethene	2.5	1.20 E-04	47
Functionalized ester	5	2.40 E-04	94

Molding Compound

Item	PPM	Method
Pb	Not detected	SGS Test Report
Cd	Not detected	SGS Test Report
Hg	Not detected	SGS Test Report
Cr+6	Not detected	SGS Test Report
PBB	Not detected	SGS Test Report
PBDE	Not detected	SGS Test Report

Die Attach Paste

Item	PPM	Method
Pb	Not detected	US EPA Method #3050B
Cd	Not detected	EN 1122:2001, Method B
Hg	Not detected	US EPA Method #3052
Cr+6	Not detected	US EPA Method #7196A, #3060A
PBB	Not detected	US EPA Method #3540 or #3550
PBDE	Not detected	US EPA Method #3540 or #3551

Laminate

Item	PPM	Method
Pb		
Cd		
Hg		
Cr+6		
PBB		
PBDE		

Package Totals

Weight (g)	PPM
2.56 E+00	1000000

STS-B-J

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Materials Declaration

Package	BGA
Body Size	27 X 27
Ball Count	297
Option	SnPbAg
Ball Size	0.6mm

Molding Compound

Item	% of Compound	Weight (g)	PPM
Silica	71	8.83900E-01	337533
Epoxy Resin	25	3.11220E-01	118845
Antimony Oxide	3	3.73500E-02	14263
Carbon Black	1	1.24489E-02	4754

Laminate

Item	% of Laminate	Weight (g)	PPM
BT-Epoxy	25	2.71E-01	103486
Glass Fiber	25	2.71E-01	103486
Copper	19	2.06E-01	78649
Nickel	11	1.19E-01	45534
Gold	7.8	8.46E-02	32288
Solder Mask (AUS5)	12.2	9.97E-02	38083

Solder Ball

	% of Solder ball	Weight (g)	PPM
Tin	62	1.75 E-01	66837
Lead	36	1.02 E-01	38808
Silver	2	5.65 E-03	2156

Bond Wires

	% of Wire	Weight (g)	PPM
Gold	99	6.01 E-03	2295

Chip

	% of Chip	Weight (g)	PPM
Si	100	3.19 E-02	12182

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	75	1.57500E-03	601
Resin	15	3.15000E-04	120
Amine	5	1.05000E-04	40
Silane	5	1.05000E-04	40

Molding Compound

Item	PPM	Method
Pb	Not detected	US EPA Method #3052
Cd	Not detected	US EPA Method #3052
Hg	Not detected	US EPA Method #3052
Cr+6	Not detected	US EPA Method #7196A, #3060A
PBB	Not detected	Analysis was performed by GC/MS
PBDE	Not detected	Analysis was performed by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	Not detected	US EPA Method #3052
Cd	Not detected	US EPA Method #3052
Hg	Not detected	US EPA Method #3052
Cr+6	Not detected	US EPA Method #7196A, #3060A
PBB	Not detected	Analysis was performed by GC/MS
PBDE	Not detected	Analysis was performed by GC/MS

Laminate

Item	PPM	Method
Pb		
Cd		
Hg		
Cr+6		
PBB		
PBDE		

Package Totals

Weight (g)	PPM
2.62 E+00	1000000

STS-B-C

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